# SN54ABT162245, SN74ABT162245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS239F - MARCH 1993 - REVISED JUNE 2004

- Members of the Texas Instruments Widebus™ Family
- A-Port Outputs Have Equivalent 25-Ω
   Series Resistors, So No External Resistors
   Are Required
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Distributed V<sub>CC</sub> and GND Pins Minimize High-Speed Switching Noise
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

#### description/ordering information

The 'ABT162245 devices are 16-bit noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or

from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses effectively are isolated.

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25- $\Omega$  series resistors to reduce overshoot and undershoot.

These devices are fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

# SN74ABT162245 . . . DGG OR DL PACKAGE (TOP VIEW)

SN54ABT162245 . . . WD PACKAGE

_			L
1DIR	]1 ~	48	10E
1B1	2	47	1A1
1B2	3	46	1A2
GND [	4	45	GND
1B3 l	5	44	1A3
1B4	6	43	1A4
V <sub>CC</sub>		42	□ v <sub>cc</sub>
1B5		41	1A5
1B6	9	40	1A6
GND [	10	39	GND
1B7 [	11	38	1A7
1B8 [	12	37	1A8
2B1 [	13	36	2A1
2B2 [	14	35	2A2
GND[	15	34	GND
2B3 [	16	33	2A3
2B4 [	17	32	2A4
v <sub>cc</sub> [	18	31	□ v <sub>cc</sub>
2B5	19	30	2A5
2B6 [	20	29	2A6
GND[	21	28	GND
2B7 [	22	27	2A7
2B8 [	23	26	2A8
2DIR [	24	25	20E

#### ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
–40°C to 85°C	CCOD DI	Tube	SN74ABT162245DL	ADT400045		
	SSOP – DL	Tape and reel	SN74ABT162245DLR	ABT162245		
	TSSOP - DGG	Tape and reel	SN74ABT162245DGGR	ABT162245		
-55°C to 125°C		Tube	SNJ54ABT162245WD	SNJ54ABT162245WD		

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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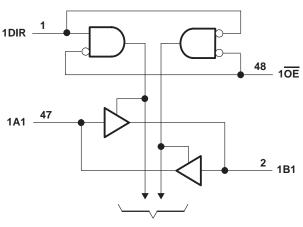
### description/ordering information (continued)

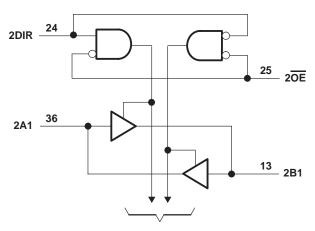
To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{\text{CC}}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### **FUNCTION TABLE** (each 8-bit section)

INP	UTS						
OE	DIR	OPERATION					
L	L	B data to A bus					
L	Н	A data to B bus					
Н	Χ	Isolation					

## logic diagram (positive logic)





**To Seven Other Channels** To Seven Other Channels

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power-off state, VO	
Current into any output in the low state, IO: SN54ABT162245 (B port)	96 mA
SN74ABT162245 (B port)	
SN54/74ABT162245 (A port)	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	
DL package	
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



# SN54ABT162245, SN74ABT162245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS239F - MARCH 1993 - REVISED JUNE 2004

# recommended operating conditions (see Note 3)

			SN54ABT	162245	SN74ABT	162245	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
٧ <sub>I</sub>	Input voltage		0	Vcc	0	Vcc	V
	I Park Town Landowski summer	B port		-24		-32	4
ЮН	High-level output current	A port		-3		-12	mA
	Lave lavel authors avenues	B port		48		64	A
lOL	Low-level output current	A port		12		12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# SN54ABT162245, SN74ABT162245 **16-BIT BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54ABT	162245	SN74ABT	162245	
PAR	AMETER	TEST CON	IDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		V <sub>CC</sub> = 5 V,	$I_{OH} = -1 \text{ mA}$	3.8			2.5		2.5		
	A		$I_{OH} = -1 \text{ mA}$	3.3			3		3		
	A port	V <sub>CC</sub> = 4.5 V	$I_{OH} = -3 \text{ mA}$	3.1			3		3.1		
			I <sub>OH</sub> = -12 mA	2.6*					2.6		V
VOH		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
	D nort		$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
	B port	$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -24 \text{ mA}$				2				
			$I_{OH} = -32 \text{ mA}$	2*					2		
	A port		I <sub>OL</sub> = 12 mA			8.0		0.8		8.0	
VOL	B port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.45		0.45		0.45	V
	Броп		I <sub>OL</sub> = 64 mA			0.55*				0.55	
V <sub>hys</sub>	-				100						mV
l <sub>i</sub>	Control inputs	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V	CC or GND			±1		±1		±1	μΑ
	A or B ports					±20		±20		±20	
IOZH§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			10		10		10	μΑ
I <sub>OZL</sub> §		$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$			-10		-10		-10	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
. «	A port	V 55V		-25	-50	-100‡	-25	-90	-25	-100	
IO¶	B port	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA
		V <sub>CC</sub> = 5.5 V,	Outputs high			2		2		2	
ICC	A or B ports	$I_{O} = 0$ ,	Outputs low			32		32		32	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2	
	Doto inputo	V <sub>CC</sub> = 5.5 V, One input at 3.4 V,	Outputs enabled			1		2		2	
∆lcc#	ΔI <sub>CC</sub> # Data inputs	Other inputs at VCC or GND	Outputs disabled			0.05		1		0.05	mA
	Control inputs	V <sub>CC</sub> = 5.5 V, One ir Other inputs at V <sub>CC</sub>				1.5		1.5		1.5	
Ci		V <sub>I</sub> = 2.5 V or 0.5 V			3						pF
Cio		$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			6						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.



 $<sup>^\</sup>dagger$  All typical values are at VCC = 5 V.  $^\ddagger$  This limit applies only to the SN74ABT162245.

<sup>§</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

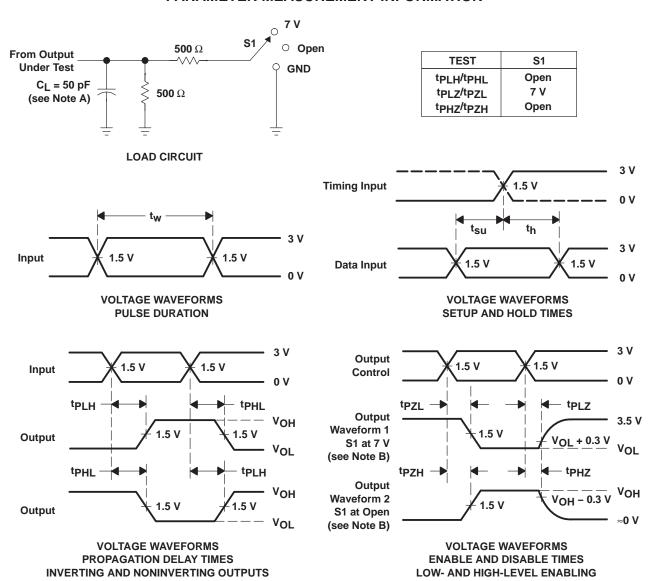
<sup>#</sup> This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

# SN54ABT162245, SN74ABT162245 **16-BIT BUŚ TRANSCEIVERS** WITH 3-STATE OUTPUTS SCBS239F - MARCH 1993 - REVISED JUNE 2004

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V(	CC = 5 V A = 25°C	<u>/,</u>	SN54ABT	162245	SN74ABT	162245	UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH		Б	1	2.2	3.4	1	4.1	1	3.9	
<sup>t</sup> PHL	Α	В	1	2.3	3.7	1	4.4	1	4.2	ns
<sup>t</sup> PLH			1	2.7	4.1	1	4.9	1	4.6	
<sup>t</sup> PHL	В	А	1.5	3.1	4.6	1.5	5.2	1.5	5.1	ns
<sup>t</sup> PZH	ŌĒ		1	3.6	5.2	1	6.4	1	6.3	
t <sub>PZL</sub>	OE	В	1	3.7	5.4	1	6.5	1	6.4	ns
<sup>t</sup> PHZ	ŌĒ	В	2	4.4	5.8	2	6.4	2	6.3	20
t <sub>PLZ</sub>	OE .	Ь	1.5	3.3	4.7	1.5	5.6	1.5	5.2	ns
<sup>t</sup> PZH			1.5	4.1	6	1.5	7.2	1.5	7.1	
t <sub>PZL</sub>	ŌĒ	A	1.5	4.3	6.1	1.5	7.3	1.5	7	ns
<sup>t</sup> PHZ	ŌĒ	^	2	4.5	6.1	2	6.8	2	6.6	ns
tPLZ	] OE	Α	1.5	3.7	5.1	1.5	6.1	1.5	5.7	

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \,\Omega$ ,  $t_f \leq 2.5 \,$ ns,  $t_f \leq 2.5 \,$ ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9677401QXA	ACTIVE	CFP	WD	48	15	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9677401QX A SNJ54ABT162245 WD	Samples
74ABT162245DLRG4	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SN74ABT162245DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SN74ABT162245DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SN74ABT162245DLG4	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SN74ABT162245DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SNJ54ABT162245WD	ACTIVE	CFP	WD	48	15	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9677401QX A SNJ54ABT162245 WD	Samples

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

# **PACKAGE OPTION ADDENDUM**

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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54ABT162245, SN74ABT162245:

Catalog: SN74ABT162245

Military: SN54ABT162245

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

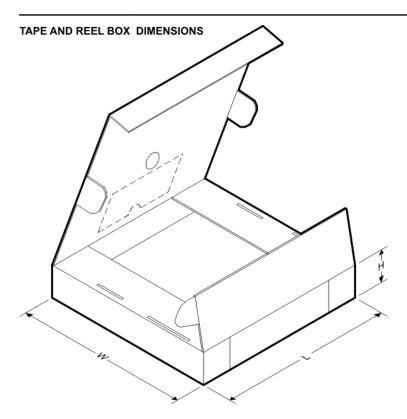
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT162245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABT162245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74ABT162245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0	
SN74ABT162245DLR	SSOP	DL	48	1000	367.0	367.0	55.0	

# PACKAGE MATERIALS INFORMATION

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### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT162245DL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74ABT162245DLG4	DL	SSOP	48	25	473.7	14.24	5110	7.87

### WD (R-GDFP-F\*\*)

#### **CERAMIC DUAL FLATPACK**

#### **48 LEADS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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